

## **AMENDMENTS TO THE SPECIFICATION**

On page 1, please replace the title with the following:

**~~--PROCESS METHOD FOR THE PRODUCTION OF A FILM--~~**

On page 1, after the title of the invention, insert the following:

### **CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a National Phase application of International Application No. PCT/DE2004/002319 filed October 19, 2004, which claims priority based on German Patent Application No. 103 49 963.6, filed October 24, 2003, which are both incorporated herein by reference.

### **BACKGROUND OF THE INVENTION**

On page 2, after line 13, insert the following:

### **SUMMARY OF THE INVENTION**

On page 7, after line 15, insert the following:

### **BRIEF DESCRIPTION OF THE DRAWINGS**

On page 7, after line 28, insert the following:

### **DETAILED DESCRIPTION OF THE INVENTION**

On page 17, please replace the two paragraphs beginning at line 11 with the following two amended paragraphs:

The film body shown in Figure 5c now forms a base film to which an electrical functional layer 97 is applied by means of one of the processes shown in Figure 1, Figure 2 or Figure 3. Figure 5c shows the resulting film body comprising the carrier film 91, the lacquer layer 92, the adhesive layer 93, the electrical functional layer 94, the semiconducting layer 95, the adhesive layer 96 and the electrical functional layer 97.

The electrical functional layer 97 here also comprises an electrically conductive material and acts as a gate electrode within the electrical component. The adhesive layer 96 is shaped with structuring in pattern form, like the electrical functional layer 97 disposed thereover. When using the processes of Figure 2 or Figure 3 however it is also possible for the adhesive layer 96 to be applied to the semiconducting layer 95 over the full surface area involved.